Radio & Wireless Week

17-20 January 2021, San Diego, CA USA
Hard Rock Hotel

IEEE MTT-S

Paper Deadline 24 July 2020

http://www.radiowirelessweek.org/

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Call For Papers

The 2021 IEEE Radio and Wireless Symposium (RWS 2021) will be held during the week of 17 January 2021 in San Diego, CA, USA.

RWS 2021 and the 21st IEEE Topical Meeting on Silicon Monolithic Integrated Circuits (SiRF 2021) are co-located and will continue to hold joint sessions. Topical conferences held in parallel provide more focused sessions in the areas of RF Power Amplifiers (PAWR), Wireless Sensors and Sensor Networks (WiSNet), and the IEEE Space Hardware and Radio Conference (SHaRC). The RWS Demonstration Track provides an interactive forum for hands-on demonstration of latest wireless experiments and innovations. There are also focus sessions on 5G and MM-Wave to THz Technologies and Applications.

RWS Papers featuring innovative work are solicited in (but not limited to) the following areas:

1. High-speed and Broadband Wireless Technologies
- 3G/4G/5G Wireless Communication Services
- Broadband Fixed Wireless and Last-Mile Access
- Optical Networks Systems and Microwave Photonics
- Ultra-High Data Rate Communications Links - Powerline Communication Technologies
- Ultra-Wideband (UWB) Systems

2. Emerging Wireless Technologies and Applications
- Femtocell and Heterogeneous Networks
- Green, Sustainable Wireless Tech. & Networks
- M2M & V2V Technologies & Applications
- Resource Management, Security
- Wireless Security and RFID Technologies

3. Wireless System Architecture and Propagation Channel Modeling
- Ad Hoc Network Techniques for Internetworking
- Distributed Network Architectures and Systems
- Frequency and Channel Allocation Algorithms
- Propagation Considerations and Fading Countermeasures
- Wireless Channel Characterization & Modeling
- Wireless Mesh and Local/Personal/Body Area Networks

4. Digital Signal Processing, SDR, & Cognitive Radio
- Digital/Analog Adaptive/Collaborative Signal Processing
- Dynamic Spectrum Sharing, Coexistence, Interoperability
- Interference Mitigation and Cancellation Techniques
- MAC, Networking protocols, Policies, Standardization
- Methods for Signal Integrity and Signal Conditioning
- Software/Hardware architectures, Algorithms
- Spectrum Sensing Technologies

5. Applications to Bio-Medical, Environmental, and Internet of Things
- Miniaturization and Integration of Wireless Technologies
- Personal Area Networks and Body area Sensor Networks
- Wireless Positioning Technologies & Remote Sensing

6. MIMO and Multi-Antenna Communications
- Cooperative/Collaborative Technology
- MIMO, MU-MIMO, Space-Time Processing - Relaying Technologies
- Multi-Beam Smart Antennas

7. Antenna Technologies
- Miniaturized, Multi-frequency and Broadband Antennas
- Passive and Active Antennas from RF to THz Frequencies
- Wireless Platform Integrated Antennas

8. Transceiver & Front-end Technologies
- Digital Transmitters for Sub-6 GHz Wireless
- Low-Power Cost-Effective IoT Solutions
- Multi-Mode Multi-Band Radios
- RF Imperfection Compensation Techniques
- Satellite Communication Systems

9. Passive Components & Packaging
- 3D-Packaging, Interconnects, and Applications
- Discrete and Highly Integrated Packaging
- Discrete, Embedded and Distributed Passive Components, Filters, Couplers and Signal Separation Devices
- Packaging of MEMS, Biosensors and Organic ICs.

10. MM-Wave to THz Technology & Applications
- Active and Passive Devices Demonstration
- Architectures for Next-Generation Large-Scale Systems
- High-Capacity Sensing and Imaging Arrays
- Phased Arrays for 5G Communication

11. 3D & Novel Engineered Materials
- Additive 3D manufacturing for wireless applications
- Novel Engineered Materials for Antenna, Packaging, Passive Devices and Flexible Electronic Integration

RWS 2021 General Chair
Nuno Borges Carvalho,
Universidade de Aveiro

RWS 2021 General Co-Chair
Kevin Chuang, *NanoSemi, Inc.*

Paper submission instructions can be found at http://www.radiowirelessweek.org/. Submissions should be formatted according to the submission review template available on the RWW website. Authors should indicate preference for oral or poster presentation. All submissions must be received by 24 July 2020. All accepted papers will be published in a digest and included in the IEEE Xplore® Digital Library. Submissions will be evaluated based on novelty, significance of the work, technical content, interest to the audience, and presentation.